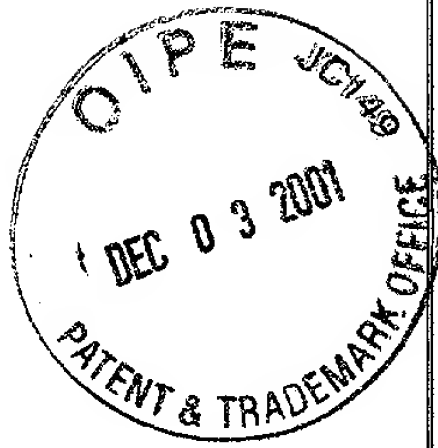


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Lee John Smith, David Albert Zoba  
Assignee: Amkor Technology, Inc.  
Title: Thin Semiconductor Package Including Stacked Dies  
Serial No.: 09/944,732 Filing Date: August 31, 2001  
Examiner: Unknown Group Art Unit: Unknown  
Docket No.: M-11443 US

San Francisco, California  
December 3, 2001

Attn: Customer Service Center  
Initial Patent Examination Division  
U.S. Patent and Trademark Office  
P.O. Box 2327  
Washington, D.C. 20231

RESPONSE TO NOTICE TO FILE CORRECTED APPLICATION PAPERS-  
FILING DATE GRANTED

Dear Sir:

In response to the "Notice to File Corrected Application Papers- Filing Date Granted" mailed by the United States Patent and Trademark Office on October 5, 2001, the following documents are enclosed:

1. 4 (Four) Sheets of Formal Drawings, consisting of Figs. 1, 2, 3, 3A, 4, 4A, 5, 6, 7, 8, and 9; and
2. Copy of Notice to File Corrected Application Papers- Filing Date Granted.

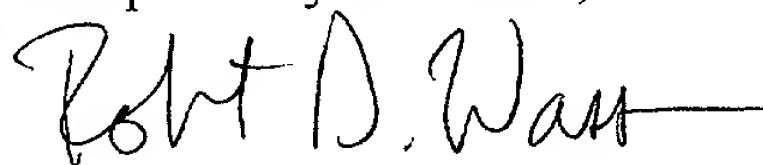
The Commissioner is hereby authorized to charge any additional fees, which may be required, or credit any overpayment to Deposit Account No. 19-2386.

It is hereby respectfully submitted that the enclosed documents overcome the noted application informality. Please telephone the undersigned at (415) 217-6000, if there are any questions. This form is being submitted in duplicate.

EXPRESS MAIL LABEL NO:

EL 873 331 583 US

Respectfully submitted,



Robert D. Wasson  
Attorney for Applicants  
Reg. No. 40,218

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